


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	ANALOG MEMS SENSORS/25/15580
1.3 Title of PCN	ST Manufacturing Reshaping (Analog_BCD6 Galvanics_AG200toSG8_All): Qualification of SG8 (Singapore) as new FE Location.
1.4 Product Category	Please refer to the impacted Products List in BCD6 Galvanics.
1.5 Issue date	2025-07-24

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO
2.1.2 Marketing Manager	Fabio CHELLI
2.1.3 Quality Manager	Alessandro PLATINI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Manufacturing reshaping program	Manufacturing reshaping program	SG8 (Singapore)

4. Description of change

	Old	New
4.1 Description	AG200 (Italy) as FE Plant	SG8 (Singapore) as FE Plant
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact. The products guarantee the same quality and electrical characteristics as per current production.	

5. Reason / motivation for change

5.1 Motivation	In the frame of ST manufacturing reshaping program (refer to Corporate PCI 15383 - Early Notification), following the continuous improvement of our service and to increase production Capacity, ST Microelectronics is announcing the qualification of SG8 (Singapore) as FE Location for the impacted Products in BCD6 Galvanics Technology. Please be advised that the enclosed list of products and dates could be subject to change. Such modifications may occur as part of the ongoing transformation program and will be communicated as and when available.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability of change will be ensured by an internal codification (Finished Good/Type) printed on the carton box label.
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7. Timing / schedule

7.1 Date of qualification results	2027-04-30
7.2 Intended start of delivery	2027-10-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)
15580 Public product.pdf 15580 Qualification Plan Detail_BCD6 Galvanics (1).pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STGAP2DM	
	STGAP2DMTR	
	STGAP2HDMTR	
	STGAP2HSCMTR	
	STGAP2HSMTR	
	STGAP2SCMTR	
	STGAP2SICDTR	
	STGAP2SICS	
	STGAP2SICSACTR	
	STGAP2SICSANCTR	
	STGAP2SICSC	
	STGAP2SICSCTR	
	STGAP2SICSNC	
	STGAP2SICSNCTR	
	STGAP2SICSNTR	
	STGAP2SICSTR	
	STGAP2SMTR	
	STGAP4STR	

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